## **IN THE CLAIMS:**

- 1. (Currently Amended) A method of adhering large seasoning bits on a food substrate, said method comprising the steps of:
  - a) mixing a dry adhesive with a plurality of three-dimensional seasoning bits to form an adhesive-bit mix wherein said bits are substantially between 1.7 to 17 mm in diameter;
    - b) cooking a food substrate having a surface to apply said bits;
    - c) applying said adhesive-bit mix to said food substrate, wherein said food substrate comprises no added water;
    - d) heating said adhesive-bit mix to a temperature above a glass transition temperature of said dry adhesive wherein said glass transition temperature is between about 40 °C to 60 °C and further wherein said dry adhesive comprises a moisture content of about 4 to 8%; and
    - e) cooling said adhesive-bit mix to a temperature below the glass transition temperature of said dry adhesive such that said dry adhesive hardens and adheres said bits to said food substrate.
- 2. (Original) The method of claim 1 further comprising the steps of:
  - f) applying a second topping to said food substrate; and
  - g) melting said second topping on said food substrate.
- 3. (Currently Amended) The method of claim 1 further comprising the steps of:
  - f) applying a non-aqueous liquid adhesive spray to said food substrate; and
  - g) applying a seasoning powder to said food substrate.
- 4. (Original) The method of claim 1 wherein said mixing of step a) is performed in a device selected from the group consisting of a mixer, a batch tumbler, a continuous tumbler, a batch blender, a continuous blender, or a ribbon blender.
- 5. (Original) The method of claim 1 wherein said adhesive-bit mix in step c) is applied via a topping unit.
- 6. (Original) The method of claim 1 wherein said cooking of said food substrate in step b) occurs by frying in a monolayer fryer.
- 7. (Original) The method of claim 1 wherein said cooking of said food substrate in step b) occurs by baking.

- 8. (Currently Amended) The method of claim 1 wherein said adhesive-bit mix comprises: about 30 to 85% three-dimensional bits; about 0 to 10% temporary non-aqueous liquid adhesive; and about 15 to 60% dry adhesive.
- 9. (Original) The method of claim 8 wherein said dry adhesive is selected from the group consisting of corn syrup solids, dextrose, sucrose, polydextrose, and mixtures thereof.
- 10. (Original) The method of claim 1 wherein said dry adhesive comprises corn syrup solids with a Dextrose Equivalent of 20 or greater.
- 11. (Original) The method of claim 1 wherein a multi-layered food substrate is made by repeating steps c) through e) at least once.
- 12. (Original) The method of claim 1 wherein said food substrate is substantially flat.
- 13. (Original) A food product made by the method of claim 1.

14. (Currently Amended) A packaged, topped snack food comprising, in proportions based upon the total weight of the topped chip:

about 5 to 30% by weight of a food substrate;

about 40 to 95% of <u>an</u> adhesive-bit mix, <u>wherein said bits are</u> substantially between 1.7 to 17 mm <u>in diameter</u> wherein said bits comprise:

about 30 to 85% three-dimensional bits;
about 0 to 10% temporary non-aqueous liquid adhesive; and
about 15 to 60% <u>a dry</u> adhesive wherein said adhesive provides an adhering
means for adhering the bits to the chip;

about 0 to 10% cheese;

about 0 to 10% non-aqueous liquid adhesive; and

about 0 to 10% seasoning powder.

- 15. (Original) The snack food in claim 14 wherein said food substrate comprises a fried food substrate.
- 16. (Original) The snack food in claim 14 wherein said food comprises a baked food substrate.
- 17. (Original) The snack food in claim 14 wherein said food substrate comprises an extruded food substrate.
- 18. (Original) The snack food claim 14 wherein said adhesive comprises corn syrup solids with a Dextrose Equivalent of 20 or greater.
- 19. (Original) The snack food in claim 14 wherein said food substrate is substantially flat.
- 20. (Original) The snack food in claim 14 wherein said food substrate comprises a food substrate cooked in a monolayer fryer.